

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	326	438/48,51,52,125,456,459.ccls. and (MEMS micromached microelectromechanical adj system) and (substrate carrier wafer board interposer) with (hole via opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:48
L2	27	29/846,852,874.ccls. and (MEMS micromached microelectromechanical adj system) and (substrate carrier wafer board interposer) with (hole via opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:50
L3	99	257/621-623,723,724,773,774.ccls. and (MEMS micromached microelectromechanical adj system) and (substrate carrier wafer board interposer) with (hole via opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:52
L4	187	"361"/\$.ccls. and (MEMS micromached microelectromechanical adj system) and (substrate carrier wafer board interposer) with (hole via opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/08 16:52